

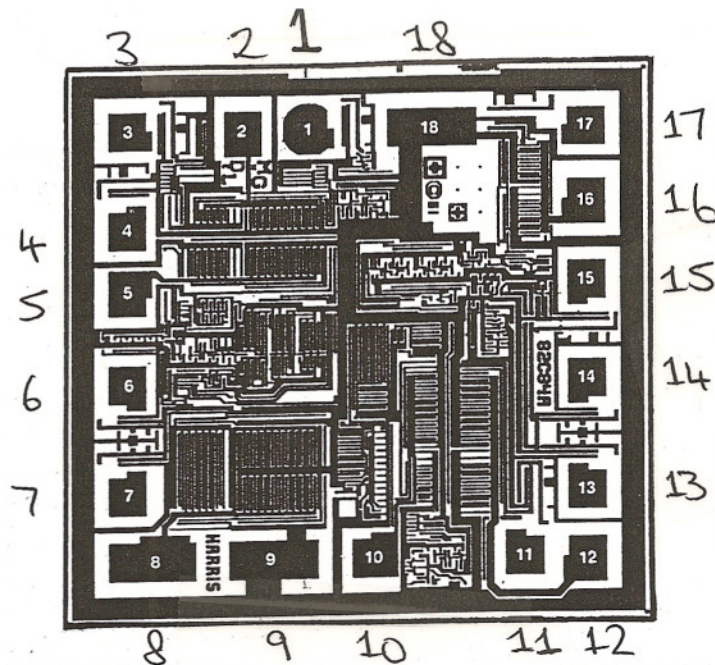


# Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423  
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

Pad	Function	Pad	Function
1	CSYNC	10	RESET
2	PCLK	11	RES
3	AENI	12	OSC
4	RDY1Y	13	F/C
5	READY	14	EFI
6	RDY2	15	ASYNC
7	AENZ	16	X2
8	CLK	17	X1
9	GND	18	V <sub>CC</sub>



E & O E. The supply of dice to this layout can only be guaranteed if it forms part of a specification or the chip identification, where given below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection, or it is the potential to which the chip back must be connected when specifically stated in a NOTE above. If no potential is given the chip back should be isolated. Nominal metallisation thicknesses are based on manufacturer's information. 1 mil. = 0.001 inch. Tolerances on dimensions +/- 3 mils.

**Topside Metal: Al**  
**Backside: Si**  
**Backside Potential:**  
**Mask Ref:**  
**Bond Pads: .004" min**

**APPROVED BY:CB**  
**MFG: HARRIS**

**DIE SIZE: .071" x .066"**  
**THICKNESS: .019"**

**DATE: 1/26/01**  
**P/N: HD82C84A-2**